

Special Issue on
**Surface Functionalization and its Electrochemical
Application**

CALL FOR PAPERS

With the development of electrochemistry, surface functionalization has affected dramatically the electrochemical process and performance. Novel surface functionalization techniques with diverse chemical approaches make the desired physical, thermal, electrical, and mechanical properties attainable. Surface modification and functionalization can also be applied to a variety of different substrates and nanoparticles for their target properties by designing appropriate chemical reactions. Meanwhile, it also serves as one of the most important key steps for further assembly process in order to make novel devices and materials.

This special issue is to attract high-quality research works from leading research groups with their work for the surface modification and the application of the functionalized surface for the application of electrochemistry. Different methods for the functionalization of the surface or the materials used for the application in electrochemical areas, including sensors and fuel cells, are all included in this special issue. Review articles which describe the current state of the art are also welcomed.

Potential topics include but are not limited to the following:

- ▶ Surface functionalized nanomaterials for electrochemical study
- ▶ Surface functionalization of different electrodes surface
- ▶ Application of the functional nanoparticles and surfaces for sensor construction, especially electrochemical sensors
- ▶ Application of the functional nanoparticles and surfaces for fuel cells
- ▶ Investigations of the stability (e.g., service life) of the proposed surface modifications

Authors can submit their manuscripts through the Manuscript Tracking System at <https://mts.hindawi.com/submit/journals/ijelc/sfsc/>.

Papers are published upon acceptance, regardless of the Special Issue publication date.

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